



Printed Circuit Boards
Interconnection Carriers

PRINTED CIRCUIT BOARDS

01

10.04.2015

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Schematic Key for Multilayer and HDI-Technology Build-Ups

| a | b | c | d | e | f | g + h+ i |
|---|---|---|---|---|---|----------|
|---|---|---|---|---|---|----------|

06 162 FR4 70 L20.35_10.35 P18_10

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

06_162_FR4_70_L20.35_10.35_p18_10

| Layers | in μ | Material | Build-Up | Assembly | | | |
|----------|-----------|----------|----------|----------|--------------------------------|----|--------------------------------|
| Layer-1 | 70 μ | Copper | | A1 | | | |
| | 100 μ | Prepreg | | | (100 μ PrePreg-Type: 2116) | | |
| Layer-2 | 100 μ | Prepreg | | | B | | |
| | 35 μ | Copper | | | | | |
| Layer-3 | 200 μ | L-FR4 | | | | A2 | |
| | 35 μ | Copper | | | | | |
| | 180 μ | Prepreg | | | | | (180 μ PrePreg-Type: 7628) |
| Layer-4 | 180 μ | Prepreg | | | | | B |
| | 180 μ | Prepreg | | | | | |
| | 180 μ | Prepreg | | | | | |
| | 100 μ | Prepreg | | | | | |
| Layer-5 | 35 μ | Copper | | A2 | | | |
| | 100 μ | L-FR4 | | | | | |
| Layer-99 | 35 μ | Copper | | | B | | |
| | 100 μ | Prepreg | | | | | |
| | 100 μ | Prepreg | | | | | |
| Layer-99 | 70 μ | Copper | | | | A1 | |